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Information Disclosure Statement By Applicant	Applicant: Nguyen et al.	
(Use Several Sheets if Necessary)	Filing Date 2/21/02	Group 2823

**U.S. Patent Documents**

Examiner Initial	No.	Patent No.	Date	Patentee	Class	Sub-class	Filing Date
DR	A	6,130,473	10/10/00	Mostafazadeh et al.	257	666	04/02/98
	B						
	C						
	D						
	E						
	F						
	G						
	H						
	I						

Foreign Patent or Published Foreign Patent Application

Examiner Initial	No.	Document No.	Publication Date	Country or Patent Office	Class	Sub-class	Translation	
	J						Yes	No

Other Documents

Examiner Initial	No.	Author, Title, Date, Place (e.g. Journal) of Publication
DR	O	"Chip Scale Package: Design, Materials, Process, Reliability, and Applications", John H. Lau and S.W. Ricky Lee, Chapter 1, Pages 1-41, (February 28, 1999) McGraw-Hill Professional Publishing; ISBN: 0070383049.
DR	P	"Fundamentals of Microsystem Packaging", Rao R. Tummala, Chapters 2, 10, and 17, (May 8, 2001) McGraw-Hill Professional Publishing; ISBN: 0071371699
	Q	
Examiner <i>DR Shi</i>		Date Considered <i>3/8/03</i>

Examiner: Initial citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.